



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSP762T	Issued	05. February 2022
MA#	MA001478834		
Package	PG-DSO-8-24	Weight*	83.36 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.265	2.72	2.72	27177	27177
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		430	
	non noble metal	iron	7439-89-6	0.717	0.86		8603	
	non noble metal	copper	7440-50-8	29.121	34.93	35.84	349335	358476
wire	noble metal	gold	7440-57-5	0.444	0.53	0.53	5331	5331
encapsulation	organic material	carbon black	1333-86-4	0.097	0.12		1165	
	plastics	epoxy resin	-	4.466	5.36		53569	
	inorganic material	silicondioxide	60676-86-0	43.976	52.75	58.23	527537	582271
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9763	9763
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7800	7800
glue	plastics	epoxy resin	-	0.134	0.16		1607	
	noble metal	silver	7440-22-4	0.631	0.76	0.92	7575	9182
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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